

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions of claims in the application.

1. (Cancelled).

2. (Cancelled).

1 ~~3~~ (Original): A quantum wire device comprising a single-crystal material made of ceramic or metal, said single-crystal material internally having dislocations arranged one-dimensionally on respective straight lines at a high density of 10^6 to 10^{14} / cm^2 , and quantum wires consisting of metal atoms introduced in said single-crystal material through a diffusion treatment, said quantum wires being arranged along said corresponding dislocations at a high density of 10^6 to 10^{14} / cm^2 .

2 ~~4~~ (Original): A thin film device comprising a single-crystal thin film made of ceramic or metal, said thin film internally having dislocations arranged one-dimensionally on respective straight lines at a high density of 10^6 to 10^{14} / cm^2 , and nano-hole bundle formed along said corresponding dislocations.

5. (Cancelled).

3 ~~6~~. (Previously presented): A method of producing a single-crystal material for a quantum wire device, comprising:

compressing a single-crystal blank made of ceramic or metal, from a direction allowing the activation of a single slip, in a temperature range of a brittle-to-ductile transition temperature to about a melting point of said single-crystal blank to induce plastic deformation therein, and subjecting the resulting product to a heat treatment at a high temperature of one-half or more of said melting point by absolute temperature, to provide a single-crystal material internally having dislocations arranged one-dimensionally on respective straight lines at a high density of 10^6 to $10^{14} / \text{cm}^2$; and

subjecting said single-crystal material to a diffusion treatment to diffuse metal atoms from the surface of said single-crystal material to form quantum wires arranged along said corresponding dislocations at a high density of 10^6 to $10^{14} / \text{cm}^2$.

4 ~~7~~. (Previously presented): A method of producing a single-crystal material for a thin film device, comprising:

compressing a single-crystal blank made of ceramic or metal, from a direction allowing the activation of a single slip, in a temperature range of a brittle-to-ductile transition temperature to about a melting point of said single-crystal blank to induce plastic deformation therein, and subjecting the resulting product to a heat treatment at a high temperature of one-half or more of said melting point by absolute temperature, to provide a single-crystal material internally having

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dislocations arranged one-dimensionally on respective straight lines at a high density of 10^6 to 10^{14} / cm^2 : and

subjecting said single-crystal material to annealing or chemical etching to form nano-hole bundles along said corresponding dislocations.